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1449A/PTO Rev. 10/95		U.S. Department of Commerce Patent and Trademark Office		Complete If Known	
LIST OF PRIOR ART CITED BY APPLICANT (use as many sheets as necessary)				Application Number	10/674,369
				Filing Date	September 29, 2003
				First Named Inventor	Jer-shen Maa
				Group Art Unit	
				Examiner Name	
Sheet	1	of	1	Attorney Docket No.	SLA.0775

OTHER PRIOR ART – NON PATENT LITERATURE DOCUMENTS

Examiner Initials	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, country where published, source.	T ²
BL		K. RIM <i>et al.</i> , <i>Strained Si for sub-100 nm MOSFETs</i> , Proceedings of the 3rd International Conference on SiGe Epitaxy and Heterostructures, Sante Fe, New Mexico, March 9-12, 2002, p125.	
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Examiner Signature		Date Considered	8/17/04
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Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

¹Unique citation designation number. ²Applicant is to place a check mark here if English language Translation is attached.

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